

# 1993 Solid State Sciences Committee Forum

## *The Restructuring of Materials Science and Technology in the United States: From Research to Manufacturing*

The next Solid State Sciences Committee (SSSC) Forum, one in a continuing series,\* will be held May 4-5, 1993 at the National Academy of Sciences in Washington, DC. The overall theme of the Forum will be "The Restructuring of Materials Science and Technology in the United States: From Research to Manufacturing." It will highlight the multiagency Advanced Materials and Processing Program (AMPP) that was developed by the Office of Science and Technology Policy (OSTP).

The OSTP report outlining the program, which was prepared by the Committee on Industrial Technology of the Federal Coordinating Council on Science, Engineering, and Technology, supplemented the President's Fiscal Year 1993 Budget Request.\*\* It cites a National Research Council report prepared under the Solid State Sciences Committee and the National Materials Advisory Board: "The AMPP draws heavily on a series of comprehensive and broad-based studies, particularly a 1989 report by the National Research Council (NRC), *Materials Science and Engineering for the 1990s: Maintaining Competitiveness in the Age of Materials*. The impact of this MS&E report has been extensive."

The Forum will begin on May 4 with a keynote address by Senator Jeff Bingaman (D, New Mexico), introduced by Robert M. White, President of the National Academy of Engineering. Top representatives from

major Federal agencies involved in the AMPP (including NSF, DOE, DARPA, and NASA) will present their perspective on the program. Other topics addressed will be the role of the national laboratories, consortia, and government technology policy in meeting society's needs in materials. A reception will be held following the first day of the Forum.

The sessions on May 5 will focus on "Challenges for Materials in the 21st Cen-



ture." Representatives from major industrial labs (Motorola, IBM, AT&T, Boeing, GE, HP) will address materials needs ranging from structural materials to semiconductors and optoelectronics. Presentations and discussion will also focus on technology transfer activities in the government labs, precompetitive R&D collaboration, the future of university research, and engineering education.

The Forum is sponsored jointly by the Solid State Sciences Committee, the National Materials Advisory Board, and the Washington Materials Forum (WMF). The WMF, organized in 1991, is a consortium of professional societies with an interest in materials science and technology. The WMF consists of the Materials Research Society, American Physical Society, American Chemical Society, American Ceramics Society, American Vacuum Society, The Metals, Mining, and Materials Society, ASM International, Society of Photo-Optical Instrumentation Engineers, Society for Hybrid Microelectronics, Mineralogical Society of America, American Institute of Chemical Engineers, American Society of Mechanical Engineers, Electro-Chemical Society, Inc., and the Federation of Materials Societies.

The fee for early registration, before **March 1, 1993**, is \$50. After March 1 the registration fee is \$75.

For a program or for more information about the Solid State Science Committee Forum, contact:

1993 SSSC Forum Board on  
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\* See *MRS Bulletin XVI* (4) (1991) p. 22.

\*\*See *MRS Bulletin XVII* (3) (1992) p. 18.

## Materials Manufacturing Forum

*to be held at 1993 MRS Spring Meeting  
Thursday, April 15, Noon to 2:00 p.m.  
San Francisco Marriott*

This special forum will feature speakers from government, industry, and national laboratories who will present the problems and progress they have encountered in their efforts to augment productivity in the manufacturing arena. An audience-wide discussion will follow. Particular issues that will be addressed include:

- **Designing materials** for ease of manufacturing
- **Transferring technology** from the laboratory to the factory
- **Converting defense-related materials and technologies** to commercial enterprises